

# DuPont™ Pyralux® HT

High Temperature Polyimide Bonding Film

Flexible Circuit Materials

## Product Description

DuPont™ Pyralux® HT Bonding Film features a thermoplastic polyimide composition that is suitable for application either as a coverlay to protect surface circuitry or bond ply for multilayer flex and rigid-flex applications. This stand-alone film exhibits low loss characteristics for high performance applications. Pyralux® HT can be used in conjunction with all-polyimide Pyralux® clads to afford a robust circuitry solution for applications requiring high operating temperature performance, excellent signal integrity, and high reliability.

## Key Features and Benefits

- > 225 °C IPC service temperature when used as bond ply with Pyralux® AP copper clad laminate
- Low loss dielectric composition
- Excellent thermal resistance from polyimide dielectric
- Certified to IPC-4203/24
- UL 94V-0, UL File E124294
- RoHS Compliant

## Packaging

Pyralux® HT Bonding Film is supplied on 24 in (610 mm) wide rolls in either 100 ft (30.5 m) or 250 ft (76 m) lengths, on nominal 3 in (76 mm) cores. Narrower widths or cut sheets are also available by special order.

## Storage and Warranty

DuPont™ Pyralux® HT Bonding Film should be stored in original packaging at temperatures of 4 - 29 °C (40 - 85 °F) and below 70% relative humidity. The product should not be refrigerated or frozen and should be kept dry, clean, and well-protected. Subject to compliance with the foregoing handling and storage recommendations, DuPont's warranties shall remain in effect for the period provided in the DuPont Standard Conditions of Sale.

**Table 1 - Standard Pyralux® HT Bonding Film Offerings**

Product Code	Dielectric Thickness μm (mil)
HT0100	25 (1.0)
HT7049	38 (1.5)
HT0200	50 (2.0)
HT0300	75 (3.0)

## Processing

Lamination conditions for DuPont™ Pyralux® HT Bonding Film are typically in the following ranges:

Part Temperature: ..... 307 - 316 °C (585 - 600 °F)

Pressure: ..... 25 - 35 kg/cm<sup>2</sup> (350 - 500 psi)

Time: ..... 1 hour, at temperature

Pyralux® HT Bonding Film processing guide available from your DuPont sales representative.

## Pyralux® HT Bonding Film Construction Selection

For further support in selecting the appropriate Pyralux® HT Bonding Film construction, please use the Laminate Product Selector at [pyralux.dupont.com](http://pyralux.dupont.com). This tool can help identify the appropriate product code for your bonding film solution.



## Safe Handling

Prior to handling, DuPont recommends referencing the Pyralux® Safe Handling Guide available at [pyralux.dupont.com](http://pyralux.dupont.com).

## Quality and Traceability

DuPont™ Pyralux® HT Bonding Film is manufactured under a certified ISO9001:2015 Quality Management System facility. Complete material and manufacturing records, which include archive samples of finished product, are maintained by DuPont. Each manufactured lot is identified for reference traceability. The packaging label serves as the primary tracking mechanism in the event of customer inquiry and includes the product name, batch number, size, and quantity.

# DuPont™ Pyralux® HT

High Temperature Polyimide Bonding Film  
Flexible Circuit Materials

## Product Performance

**Table 2 - DuPont™ Pyralux® HT Bonding Film Properties**

Property	HT0100 Typical Value	Test Method
Dielectric Constant (Dk)		
1 MHz	3.2	IPC-TM-650 2.5.5.3
10 GHz	3.2	ASTM D2520
Loss Tangent (Df)		
1 MHz	0.0015	IPC-TM-650 2.5.5.3
10 GHz	0.0015	ASTM D2520
Peel Strength* (Adhesion to Copper)		
As Received, N/mm (lb/in)	1.4 (8)	IPC-TM-650 2.4.9
After Solder, N/mm (lb/in)	1.4 (8)	
As Received (Alternative Oxide Cu Surface), N/mm (lb/in)	1.1 (6)	
Adhesive Flow, mm (mil)	0.01 (0.25)	IPC-TM-650 2.3.17.1
Coefficient of Thermal Expansion		
XY-Axis - 50 to 250 °C, ppm/°C	65	IPC-TM-650 2.4.41
Z-Axis, ppm/°C	Below Tg 54 / Above Tg 230	IPC-TM-650 2.4.24
Solder Float, 320 °C for 60 s	Pass	IPC-TM-650 2.4.13
Moisture Absorption, %	0.8	IPC-TM-650 2.6.2
Dielectric Strength, V/μm	161 - 275	ASTM D149
Tensile Modulus, GPa	2.8	IPC-TM-650 2.4.19
Tensile Strength, MPa	165	IPC-TM-650 2.4.19
Elongation, %	170	IPC-TM-650 2.4.19
Flexural Endurance, cycles	570 - 580	IPC-TM-650 2.4.24.6
Glass Transition Temperature (Tg), °C	233	IPC-TM-650 2.4.24c
Decomposition Temperature (2 % / 5 %), °C	548 / 579	ASTM D3850 (In Air)

Data within this table are typical values for the listed product. Performance can vary depending on construction and processing.

\*Peel strength values generated after lamination to treated side of 1 oz RA copper foil.



For more information on DuPont™ HT Bonding Film or other DuPont products, please visit our website.

[pyralux.dupont.com](http://pyralux.dupont.com)

The information provided in this data sheet corresponds to our knowledge on the subject at the date of its publication. It may be subject to revision as new knowledge and experience becomes available. This information is not intended to substitute for any testing you may need to conduct to determine for yourself the suitability of our products for your particular purposes. Since we cannot anticipate all variations in end-use and disposal conditions, DuPont makes no warranties and assumes no liability in connection with any use of this information. It is intended for use by persons having technical skill, at their own discretion and risk. Nothing in this publication is to be considered as a license to operate under or a recommendation to infringe any patent right.

CAUTION: Do not use in medical applications involving permanent implantation in the human body. For other medical applications, see "DuPont Medical Caution Statement," H-50102-5 and "DuPont Policy Regarding Medical Applications" H-50103-5.

DuPont™, the DuPont Oval Logo, and all products, unless otherwise noted, denoted with ™, ® or ® are trademarks, service marks or registered trademarks of affiliates of DuPont de Nemours, Inc. Copyright © 2025 DuPont de Nemours Inc. All rights reserved.

EI-10127 (2/25)